PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6819892

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CONG WANG	06/15/2021
XINYU WANG	06/09/2021
YUEFENG DU	06/10/2021

RECEIVING PARTY DATA

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State/Country:	HONG KONG

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17357956

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ATTORNEY DOCKET NUMBER:	HP0170US (4702-04400)
NAME OF SUBMITTER:	MICHAEL W. PIPER
SIGNATURE:	/Michael W. Piper/
DATE SIGNED:	07/19/2021

Total Attachments: 6
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ASSIGNMENT

WHEREAS, I, among the following inventors, Cong WANG, Xinyu WANG, Yuefeng DU am an inventor of **SECURE WEB FRAMEWORK** (the "Invention"); and

WHEREAS, CITY UNIVERSITY OF HONG KONG, a company created and existing under and by virtue of the laws of Hong Kong, is desirous of acquiring the entire right, title and interest in and to the aforesaid Invention throughout the world, and all right, title and interest in, to and under any and all Letters Patent of the United States and all other countries throughout the world;

IN CONSIDERATION OF one dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I hereby sell, assign, transfer and set over to CITY UNIVERSITY OF HONG KONG, all right, title and interest in and to the said Invention throughout the world, as well as any and all other applications for said Invention, including divisional, continuation, continuation-in-part, provisional, non-provisional, regular, renewal, reissue applications, extensions, national stage applications, and the like and any and all Letters Patent of the United States and foreign countries which may be granted therefor, and all international rights of priority associated with said Invention, applications, patents and like protection, the same to be held and enjoyed by CITY UNIVERSITY OF HONG KONG for its own use and benefit, and for the use and benefit of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Letters Patent of the United States or foreign countries are or may be granted or reissued, as fully and entirely as the same would have been held and enjoyed if this assignment and sale had not been made.

And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all Letters Patent of the United States on said Invention or resulting from said application and from any and all divisions, continuations, and reissues thereof, to CITY UNIVERSITY OF HONG KONG, as assignee of my entire interest, and hereby covenant that I have the full right to convey the entire interest herein assigned, and that I have not executed and will not execute any agreement in conflict herewith.

And I further hereby covenant and agree that I will, at any time, upon request, execute and deliver any and all papers that may be necessary or desirable to perfect the title of said Invention and to such Letters Patent as may be granted therefor, to CITY UNIVERSITY OF HONG KONG, its successors, assigns, or other legal representatives and that if CITY UNIVERSITY OF HONG KONG, its successors, assigns or other legal representatives shall desire to file any divisional or continuation applications or to secure a reissue of such Letters Patent, or to file a disclaimer relating thereto, I will upon request, sign all papers, make all rightful oaths and do all lawful acts requisite for the filing of such divisional or continuation application, or such application for reissue and the procuring thereof, and for the filing of such disclaimer, without further compensation but at the expense of said assignee, its successors, or other legal representatives.

And I do further covenant and agree that I will, at any time upon request, communicate to CITY UNIVERSITY OF HONG KONG, its successors, assigns or other legal representatives, such facts relating to said Invention and Letters Patent or the file history thereof as may be known to me, and testify as to the same in any interference or other litigation when requested so to do, without further compensation but at the expense of said assignee, its successors, or other legal representatives.

ASSIGNEE:

(Signature):________________ Date: 16 Jan 2021

(Printed Name): Victor Lau

(Designation/Title): Associate Director of Knowledge Transfer Office,
City University of Hong Kong

For the: CITY UNIVERSITY OF HONG KONG

ASSIGNOR1

(Signature):______________ Date: Jun 15th, 2021

(Printed Name): Cong WANG

(Designation): Inventor

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ASSIGNOR2

(Signature):________________ Date: 2021/6/19

(Printed Name): Xinyu WANG

(Designation): Inventor

ASSIGNOR3

(Signature):________________ Date: 2021/06/10

(Printed Name): Yuefeng DU

(Designation): Inventor